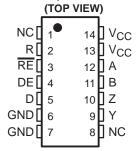
SLLS378C - MAY 2000 - REVISED JUNE 2002

- High-Speed Low-Power LinBICMOS™
 Circuitry Designed for Signaling Rates[†] of up to 30 Mbps
- Bus-Pin ESD Protection Exceeds 12 kV HBM
- Very Low Disabled Supply-Current Requirements . . . 700 μA Maximum
- Designed for High-Speed Multipoint Data Transmission Over Long Cables
- Common-Mode Voltage Range of –7 V to 12 V
- Low Supply Current . . . 15 mA Max
- Compatible With ANSI Standard TIA/EIA-485-A and ISO 8482:1987(E)
- Positive and Negative Output Current Limiting
- Driver Thermal Shutdown Protection

description

The SN65LBC180A and SN75LBC180A differential driver and receiver pairs are monolithic integrated circuits designed for bidirectional data communication over long cables that take on the characteristics of transmission lines. They are balanced, or differential, voltage mode devices that are compatible with ANSI standard TIA/EIA-485-A and ISO 8482:1987(E). The A version offers improved switching performance over its predecessors without sacrificing significantly more power.

SN65LBC180AD (Marked as BL180A) SN65LBC180AN (Marked as 65LBC180A) SN75LBC180AD (Marked as LB180A) SN75LBC180AN (Marked as 75LBC180A)



NC-No internal connection

Function Tables DRIVER

INPUT	ENABLE	OUTPUTS
D	DE	ΥZ
Н	Н	H L
L	Н	L H
X	L	Z Z
Open	Н	H L

RECEIVER

DIFFERENTIAL INPUTS A-B	ENABLE RE	OUTPUT R
V _{ID} ≥ 0.2 V	L	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	L	?
$V_{ID} \le -0.2 V$	L	L
X	Н	Z
Open circuit	L	Н

H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

These devices combine a differential line driver and differential input line receiver and operate from a single 5-V power supply. The driver differential outputs and the receiver differential inputs are connected to separate terminals for full-duplex operation and are designed to present minimum loading to the bus when powered off ($V_{CC}=0$). These parts feature wide positive and negative common-mode voltage ranges, making them suitable for point-to-point or multipoint data bus applications. The devices also provide positive and negative current limiting for protection from line fault conditions. The SN65LBC180A is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

† Signaling rate by TIA/EIA-485-A definition restrict transition times to 30% of the bit duration, and much higher signaling rates may be achieved without this requirement as displayed in the *TYPICAL CHARACTERISTICS* of this device.

LinBiCMOS is a trademark of Texas Instruments.

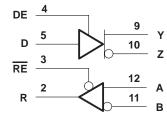


SLLS378C - MAY 2000 - REVISED JUNE 2002

logic symbol[†]

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

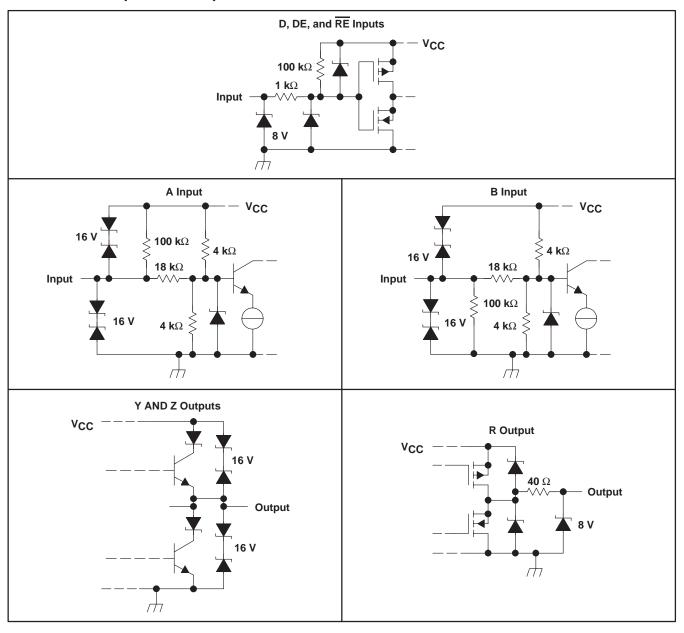


AVAILABLE OPTIONS

	PACKAGE					
TA	SMALL OUTLINE† (D)	PLASTIC DUAL-IN-LINE (N)				
0°C to 70°C	SN75LBC180AD	SN75LBC180AN				
-40°C to 85°C	SN65LBC180AD	SN65LBC180AN				

[†]The D package is available taped and reeled. Add an R suffix to the part number (i.e., SN65LBC180ADR).

schematics of inputs and outputs



SLLS378C - MAY 2000 - REVISED JUNE 2002

absolute maximum ratings†

Supply voltage range, V _{CC} (see Note 1)	
Input voltage range, V _I (A, B)	
Voltage range at D, R, DE, RE	$-0.3 \text{ V to V}_{CC} + 0.5 \text{ V}$
Continuous total power dissipation (see Note 2)	Internally limited
Total power dissipation	See Dissipation Rating Table
Electrostatic discharge: Bus terminals and GND, Class 3, A: (see Note 3)	
Bus terminals and GND, Class 3, B: (see Note 3)	400 V
All terminals, Class 3, A:	3 kV
All terminals, Class 3, B:	
Storage temperature range, T _{stq}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND except for differential input or output voltages.

3. Tested in accordance with MIL-STD-883C, Method 3015.7

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{$A$}} \leq 25^{\circ}\mbox{$C$}$ POWER RATING	DERATING FACTOR‡ ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
D	950 mW	7.6 mW/°C	608 mW	494 mW
N	1150 mW	9.2 mW/°C	736 mW	598 mW

[‡]This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
High-level input voltage, V _{IH}	D, DE, and RE	2		VCC	V
Low-level input voltage, V _{IL}	D, DE, and RE	0		0.8	V
Differential input voltage, V _{ID} (see Note 4)		-12§		12	V
Voltage at any bus terminal (separately or common mode), VO, VI, or VIC	A, B, Y, or Z	-7		12	V
High level autout august 1	Y or Z	-60			A
Low-level input voltage, V _{IL} D, DE, and Differential input voltage, V _{ID} (see Note 4) Voltage at any bus terminal (separately or common mode), V _O , V _I , or V _{IC} A, B, Y, or Z Y or Z R Low-level output current, I _{OL} Y or Z R SN65LBC18	R	-8			mA
Law level autout compat. I	Y or Z			60	^
High-level output current, I _{OL}	R			8	mA
Occupation from air temperature T	SN65LBC180A	-40		85	00
Operating free-air temperature, T _A	SN75LBC180A	0	•	70	°C

[§] The algebraic convention where the least positive (more negative) limit is designated minimum, is used in this data sheet. NOTE 4: Differential input/output bus voltage is measured at the noninverting terminal with respect to the inverting terminal.



^{2.} The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature.

SLLS378C - MAY 2000 - REVISED JUNE 2002

driver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
VIK	Input clamp voltage	$I_{I} = -18 \text{ mA}$		-1.5	-0.8		V
		$R_L = 54 \Omega_{r}$	SN65LBC180A	1	1.5	3	
.,,	Differential output voltage	See Figure 1	SN75LBC180A	1.1	1.5	3	.,
VOD	magnitude	$R_L = 60 \Omega_{r}$	SN65LBC180A	1	1.5	3	V
		See Figure 2	SN75LBC180A	1.1	1.5	3	
Δ V _{OD}	Change in magnitude of differential output voltage (see Note 5)	See Figures 1 and 2	See Figures 1 and 2			0.2	V
V _{OC} (SS)	Steady-state common-mode output voltage			1.8	2.4	2.8	V
ΔVOC	Change in steady-state common-mode output voltage (see Note 5)	See Figure 1	-0.1		0.1	V	
IO	Output current with power off	$V_{CC} = 0$,	$V_0 = -7 \text{ V to } 12 \text{ V}$	-10		10	μΑ
lн	High-level input current	V _I = 2 V		-100			μΑ
I _I L	Low-level input current	V _I = 0.8 V		-100			μΑ
los	Short-circuit output current	-7 V ≤ V _O ≤ 12 V		-250	±70	250	mA
			Receiver disabled and driver enabled		5.5	9	
ICC	Supply current	$V_I = 0$ or V_{CC} , No load	Receiver disabled and driver disabled		0.5	0.5 1 m	
			Receiver enabled and driver enabled		8.5	15	

 $^{^{\}dagger}$ All typical values are at VCC = 5 V and TA = 25°C.

NOTE 5: $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in the steady-state magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

driver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output		2	6	12	ns
t _{PHL}	Propagation delay time, high-to-low-level output		2	6	12	ns
t _{sk(p)}	Pulse skew (tpLH - tpHL)	$R_L = 54 \Omega$, $C_L = 50 pF$, See Figure 3		0.3	1	ns
t _r	Differential output signal rise time	Oce rigule 3	4	7.5	11	ns
t _f	Differential output signal fall time		4	7.5	11	ns
^t PZH	Propagation delay time, high-impedance-to-high-level output	R_L = 110 Ω, See Figure 4		12	22	ns
t _{PZL}	Propagation delay time, high-impedance-to-low-level output	R_L = 110 Ω, See Figure 5		12	22	ns
^t PHZ	Propagation delay time, high-level-to-high-impedance output	R_L = 110 Ω, See Figure 4		12	22	ns
tPLZ	Propagation delay time, low-level-to-high-impedance output	R_L = 110 Ω, See Figure 5		12	22	ns

SLLS378C - MAY 2000 - REVISED JUNE 2002

receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER			TEST CONDITIONS		TYP	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	$I_O = -8 \text{ mA}$				0.2	V
VIT-	Negative-going input threshold voltage	I _O = 8 mA		-0.2			V
V _{hys}	Hysteresis voltage (V _{IT+} – V _{IT-})				50		mV
٧ _{IK}	Enable-input clamp voltage	$I_{ } = -18 \text{ mA}$		-1.5	-0.8		V
Vон	High-level output voltage	$V_{ID} = 200 \text{ mV},$	$I_{OH} = -8 \text{ mA}$	4	4.9		V
VOL	Low-level output voltage	$V_{ID} = -200 \text{ mV},$	I _{OL} = 8 mA		0.1	8.0	V
I _{OZ}	High-impedance-state output current	$V_O = 0 V \text{ to } V_{CC}$		-1		1	μА
lΗ	High-level enable-input current	V _{IH} = 2.4 V		-100			μΑ
I _I L	Low-level enable-input current	V _{IL} = 0.4 V		-100			μΑ
		V _I = 12 V, V _{CC} = 5 V			0.4	1	
		V _I = 12 V, V _{CC} = 0 V			0.5	1	
i _l	Bus input current	V _I = -7 V, V _{CC} = 5 V	Other input at 0 V	-0.8	-0.4		mA
		$V_I = -7 \text{ V},$ $V_{CC} = 0 \text{ V}$		-0.8	-0.3		
			Receiver enabled and driver disabled		4.5	7.5	
ICC	Supply current	$V_I = 0$ or V_{CC} , No load	V _I = 0 or V _{CC} , Receiver disabled and driver disabled		0.5	1	mA
1		110 1000	Receiver enabled and driver enabled		8.5	15	

 $[\]dagger$ All typical values are at V_{CC} = 5 V and T_A = 25°C.

receiver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDI	MIN	TYP	MAX	UNIT	
tPLH	Propagation delay time, low- to high-level output			7	13	20	ns
tPHL	Propagation delay time, high- to low-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$	See Figure 7	7	13	20	ns
tsk(p)	Pulse skew (tpHL - tpLH)				0.5	1.5	ns
t _r	Output signal rise time	0 5			2.1	3.3	ns
tf	Output signal fall time	See Figure 7		2.1	3.3	ns	
^t PZH	Output enable time to high level				30	45	ns
tPZL	Output enable time to low level	C 10 pF	Soo Figuro 9		30	45	ns
tPHZ	Output disable time from high level	C _L = 10 pF, See Figure 8			20	40	ns
t _{PLZ}	Output disable time from low level				20	40	ns

PARAMETER MEASUREMENT INFORMATION

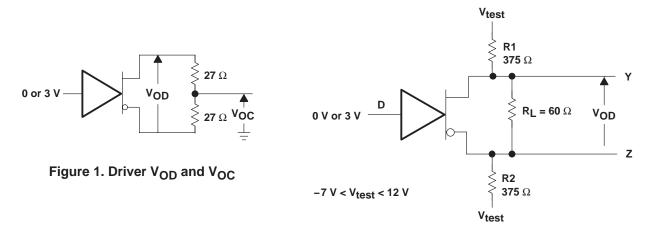
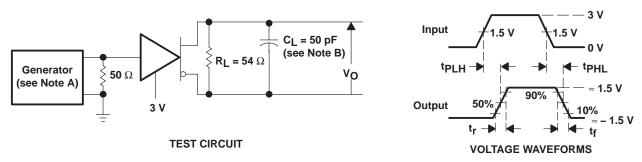
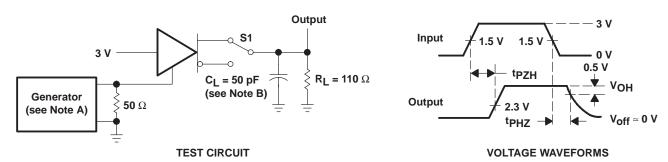


Figure 2. Driver VOD



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$
 - B. C_L includes probe and jig capacitance.

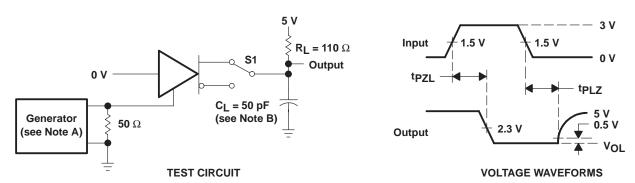
Figure 3. Driver Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$
 - B. C_I includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{f} \leq$ 6 ns, $t_{f} \leq$ 7 ns, $t_{f} \leq$ 8 ns, $t_{f} \leq$ 8 ns, $t_{f} \leq$ 9 ns, $t_$
 - B. C_L includes probe and jig capacitance.

Figure 5. Driver Test Circuit and Voltage Waveforms

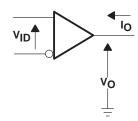
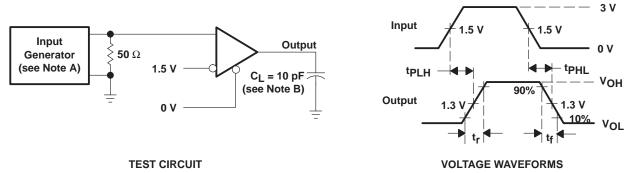


Figure 6. Receiver VOH and VOL

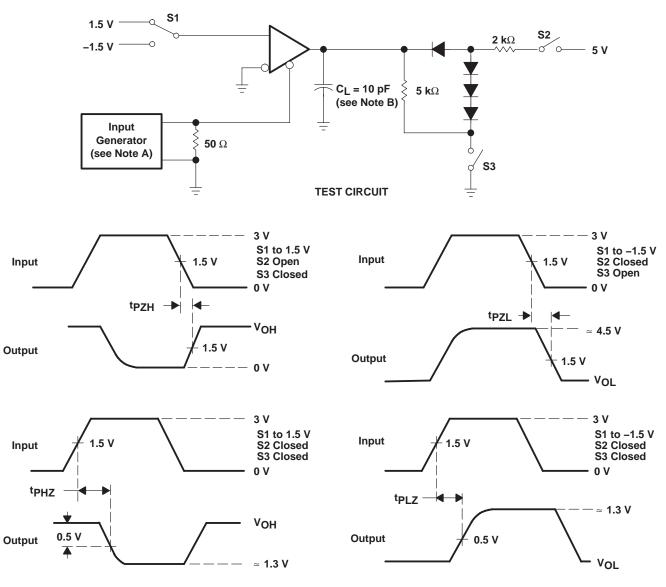


- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$
 - B. C_L includes probe and jig capacitance.

Figure 7. Receiver Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 8 ns, $t_f \leq$ 9 ns, t_f

B. CL includes probe and jig capacitance.

Figure 8. Receiver Output Enable and Disable Times

TYPICAL CHARACTERISTICS

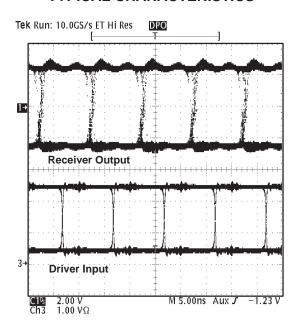
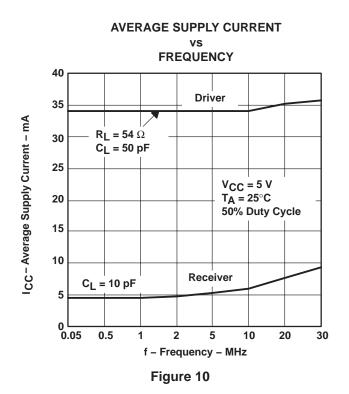


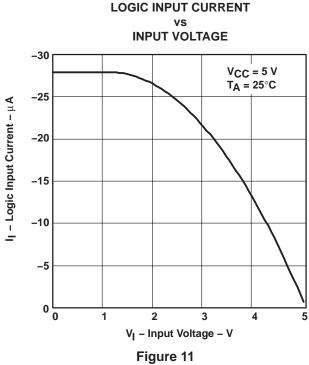


Figure 9. Typical Waveform of Nonreturn-to-Zero (NRZ), Pseudorandom Binary Sequence (PRBS) Data at 100 Mbps Through 15m, of CAT 5 Unshielded Twisted Pair (UTP) Cable

TIA/EIA-485-A defines a maximum signaling rate as that in which the transition time of the voltage transition of a logic-state change remains less than or equal to 30% of the bit length. Transition times of greater length perform quite well even though they do not meet the standard by definition.

TYPICAL CHARACTERISTICS





BUS INPUT CURRENT INPUT VOLTAGE 800 $V_{CC} = 5 V$ 600 T_A = 25°C I _ Bus Input Current – μ A 400 200 0 -200 -400-600 -8 -6 -4 -2 0 2 4 6 8 10

V_I - Input Voltage - V

Figure 12



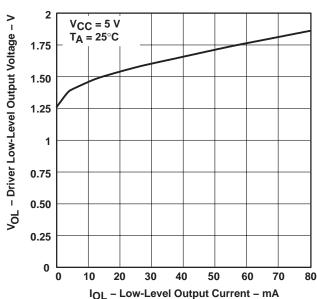
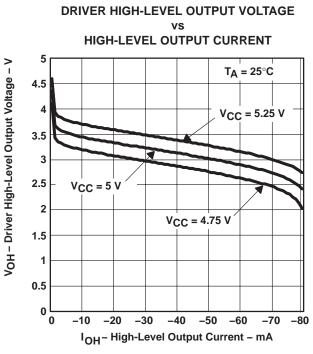
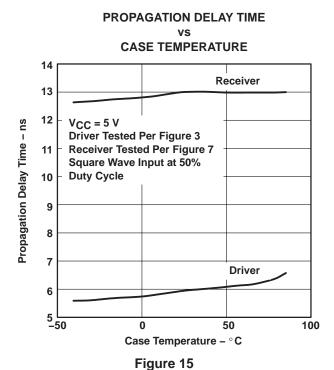


Figure 13

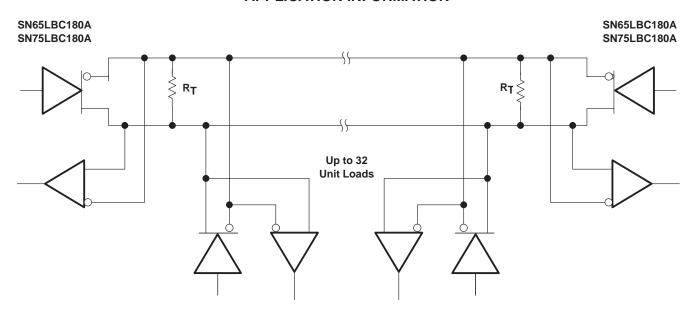
TYPICAL CHARACTERISTICS





SLLS378C - MAY 2000 - REVISED JUNE 2002

APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance ($R_T = Z_O$). Stub lengths off the main line should be kept as short as possible. One SN65LBC180A typically represents less than one unit load.

Figure 16. Typical Application Circuit

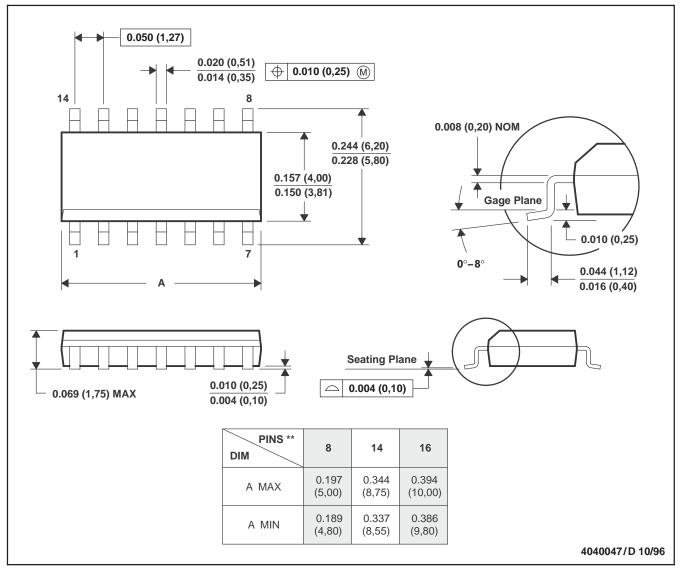
SLLS378C - MAY 2000 - REVISED JUNE 2002

MECHANICAL DATA

D (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

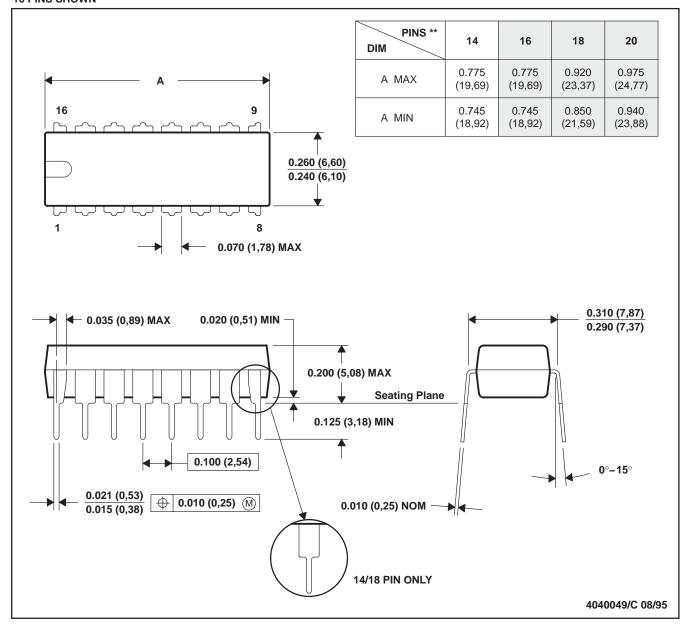
SLLS378C - MAY 2000 - REVISED JUNE 2002

MECHANICAL DATA

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 (20-pin package is shorter than MS-001).





com 18-Jul-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LBC180AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC180ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC180ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC180ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC180AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65LBC180ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75LBC180AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC180ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC180ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC180ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC180AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75LBC180ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



PACKAGE OPTION ADDENDUM

18-Jul-2006

ng out of such information e	exceed the total purchas	se price of the TI part(s)	at issue in this docum	ent sold by T
	ng out of such information e	ng out of such information exceed the total purchase	ng out of such information exceed the total purchase price of the TI part(s)	ng out of such information exceed the total purchase price of the TI part(s) at issue in this docum



TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LBC180ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN65LBC180ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75LBC180ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75LBC180ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LBC180ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN65LBC180ADR	SOIC	D	14	2500	333.2	345.9	28.6
SN75LBC180ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN75LBC180ADR	SOIC	D	14	2500	333.2	345.9	28.6

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products Amplifiers amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated